

uCPE-ID1100 Medium/Small – Xeon-D

**Technical Specification of
uCPE-ID1100-Medium/Small**

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1 Introduction

The following is a technical specification for the uCPE-ID1100 Medium/Small. This document provides technical details on the platform.

2 uCPE-ID1100 Medium Specification

Feature:	
CPU:	Intel Xeon D-1541 8Cores, 16 threads Base Freq. 2.1GHz, 14MB Cache, TDP 45W Platform will also support Xeon-D NS SKU's
BIOS:	UEFI BIOS
BIOS Flash:	SPI
Switch Chips set:	Broadcom Hurricane2 BCM56160
Copper PHY:	Embedded CuGPHY, BCM56160
MGMT PHY	Broadcom B50210S
Memory,	32GB DDR4 with ECC 2x channels DDR4 DIMMs 2 x 16GByte SODIMM
Storage	512GB /SSD, M2, SATA
Internal Switch	2x 10GE-KR Additional 2x10GE-KR with Xeon-D NS SKU's
External Switch Ports	10x 1GbE RJ45 4x SFP+ 4 of 1GbE supports POE+* *Total Power POE+ power limit is 65W Dynamic power load based on actual power consumption.
Host Mgmt	1GbE RJ45 on Management Card, Shared with BMC. 1GbE Between BMC and Switch
USB 3.0	2xFront, 2x Internal Vertical
Serial Console	RJ45 connector using RS232 signaling
LTE	M.2 Key-B, support 3042 Card. Externally accessible SIM card supported.

	Mini PCIe supporting USB2.0/3.0 and externally accessible SIM card.
WiFi	Not supported
M.2 Expansion	M.2 Key B with support up to 30x110mm. Currently used for M.2 Storage
BMC	µBMC
TPM	TPM 2.0 – Compute TPM2.0 - Module
Power	90-264VAC input, 12VDC, 125W 54VDC, 65W Dying Gasp supported on BMC
LED's	Management card support three tri-color configurable LED's (red, green, blue)
Other Hardware:	Configurable Recessed button (Recommend for Factory reset) Configurable Large button (Recommend for power)
Form Factor:	1U rackmount Form Factor EIA 19" Depth 410mm
Expansion / Voice Module	PCIe x16: Support for either Voice module or 2/ M4 module. Support for Voice module is connected directly to the CPU board. In order to support M4 module, needs to install mid plan expansion kit. Mid plan kit is not part of BOM.
Weight:	5.46kg (192.6oz)
Power Consumption:	Maximum: 90-130Vac 50-60Hz 4.6A / 200-240Vac 50-60Hz 2.4A Typical: 90-130Vac 50-60Hz 2.2A / 200-240Vac 50-60Hz 1.1A The total power consumption of the card depends on user application
Cooling:	FANs, Number of Fans TBD, Design supports 5 FAN
Sensors/Monitors:	Thermal protection Critical Error Detection Voltage monitors

	Current protection
Operating Temperature:	0°C – 40°C (32°F - 104°F)
Storage:	-40°C–65°C (-40°F–149°F)
Operating Altitude	10000 ft (3048 m)
Regulation:	CE, FCC Class A, ROHS requirements.
MTBF*:	57156 hours * According to Telcordia SR-332 Issue 4. Environmental condition – GB (Ground, Fixed, and Controlled). Ambient temperature 40°C



Figure 1 uCPE-ID1100 Medium/Small Front View



Figure 2 uCPE-ID1100 Medium/Small Rear View

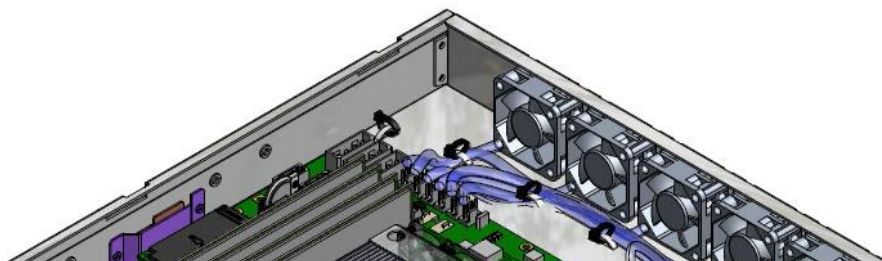


Figure 3 uCPE-ID1100 Medium/Small 3D Views

2.1 vECPE Small Ordering Information

P/N	Description	Notes:
80500-0179-G20	vECPE, 1U,19",D1517(4C),DDR4/16GB/ECC,2xPS	Top level – Shippable kit, including packaging, GA candidate.

P/N	Description	Notes:
80500-0180-G20	vECPE, 1U,19",D1541(8C),DDR4/32GB/ECC,2xPS	Top level – Shippable kit, including packaging, GA candidate.